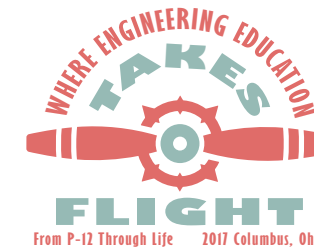


SPONSORED TECH SESSIONS



TUESDAY, JUNE 27TH

For further information on each sponsor technical session, please visit the Online Session Locator at www.asee.org/osl and enter the session code below.

SUNDAY, JUNE 25TH

U372-SPONSOR TECHNICAL SESSION: Technology Powering Education: Leveraging MATLAB for Increased Productivity - Presented by Mathworks
Sun. June 25, 2017 11:30 AM to 1:00 PM
Room A120, Columbus Convention Center

U572A-SPONSOR TECHNICAL SESSION: Teaching Engineering Ethics through the Case Study Method - Presented by Ohio State
Sun. June 25, 2017 2:30 PM to 3:45 PM
Room A121, Columbus Convention Center

U572B-SPONSOR TECHNICAL SESSION: Engineering Entrepreneurship - Presented by Texas A&M Engineering
Sun. June 25, 2017 2:30 PM to 3:45 PM
Room A120, Columbus Convention Center

U572C-SPONSOR TECHNICAL SESSION: Getting Started with TI LaunchPad™ development kit - Presented by Texas Instruments
Sun. June 25, 2017 2:30 PM to 3:45 PM
Room A111, Columbus Convention Center

MONDAY, JUNE 26TH

M372A-SPONSOR TECHNICAL SESSION: Using the FE Exam for Effective Outcomes Assessment - Presented by NCEES
Mon. June 26, 2017 11:30 AM to 1:00 PM
Room A120, Columbus Convention Center

M372C-SPONSOR TECHNICAL SESSION: Sparking Innovation in the Class of 2020 through Mechatronics and IoT - Presented by National Instruments
Mon. June 26, 2017 11:30 AM to 1:00 PM
Room A121, Columbus Convention Center

M472A-SPONSOR TECHNICAL SESSION: The Future of Engineering Curricula - Presented by Purdue University
Mon. June 26, 2017 1:30 PM to 3:00 PM
Room A120, Columbus Convention Center

M472B-SPONSOR TECHNICAL SESSION: Texas A&M-Chevron Engineering Academy Program - Presented by Texas A&M Engineering
Mon. June 26, 2017 1:30 PM to 3:00 PM
Room A121, Columbus Convention Center

M572-SPONSOR TECHNICAL SESSION: The Future of Engineering Faculty - Presented by Purdue University
Mon. June 26, 2017 3:15 PM to 4:45 PM
Room A120, Columbus Convention Center

M572A-SPONSOR TECHNICAL SESSION: Implementing Open-ended Design Projects in First-year Engineering - Presented by Ohio State
Mon. June 26, 2017 3:15 PM to 4:45 PM
Room A121, Columbus Convention Center

M772A-SPONSOR TECHNICAL SESSION: Bringing Hands on Engineering to K-12 and Outreach Programs with TI Calculator & Innovator Hub - Presented by Texas Instruments
Mon. June 26, 2017 6:00 PM to 7:30 PM
Room A120, Columbus Convention Center

M772B-SPONSOR TECHNICAL SESSION: Basic System-on-Chip (SoC) Design Education Kit from ARM University Program - Presented by ARM Ltd, Cambridge UK, and Numato Lab, Electronics City, Bangalore India
Mon. June 26, 2017 6:00 PM to 7:30 PM
Room A121, Columbus Convention Center

T172A-SPONSOR TECHNICAL SESSION: Exploring Data Visualization Approaches to Enhance Student Engagement - Presented by McGraw-Hill Education
Tue. June 27, 2017 8:00 AM to 9:30 AM
Room A121, Columbus Convention Center

T172B-SPONSOR TECHNICAL SESSION: Bringing Power and Signal Chain to Your Classroom - Presented by Texas Instruments
Tue. June 27, 2017 8:00 AM to 9:30 AM
Room A120, Columbus Convention Center

T172C-SPONSOR TECHNICAL SESSION: The Future of Engineering Professional Education - Presented by Purdue University
Tue. June 27, 2017 8:00 AM to 10:00 AM
Room A216, Columbus Convention Center

T372A-SPONSOR TECHNICAL SESSION: Graduate Students and Communication Skills - Presented by Purdue University
Tue. June 27, 2017 10:00 AM to 12:00 PM
Room A216, Columbus Convention Center

T472A-SPONSOR TECHNICAL SESSION: Assessing Professional Skills - Presented by Ohio State
Tue. June 27, 2017 1:30 PM to 3:00 PM
Room A121, Columbus Convention Center

T472B-SPONSOR TECHNICAL SESSION: Engineering Licensure: Education, Examinations, and Experience - Presented by NCEES
Tue. June 27, 2017 1:30 PM to 3:00 PM
Room A120, Columbus Convention Center

T472C-SPONSOR TECHNICAL SESSION: The Future of Facilities and Staff-inspired Transformations - Presented by Purdue University
Tue. June 27, 2017 1:00 PM to 3:00 PM
Room A216, Columbus Convention Center

T572A-SPONSOR TECHNICAL SESSION: Panel discussion: Instructors talk learning technology and its impact on student performance - Presented by McGraw-Hill Education
Tue. June 27, 2017 3:15 PM to 4:45 PM
Room A121, Columbus Convention Center

T572B-SPONSOR TECHNICAL SESSION: Preparing Students for Engineering System Design through Power Electronics - Presented by National Instruments
Tue. June 27, 2017 3:15 PM to 4:45 PM

T572C-SPONSOR TECHNICAL SESSION: NC State Engineering - Applying Research to Practice in Programs
Tue. June 27, 2017 3:15 PM to 4:45 PM
Union B, Hyatt Regency Columbus

T572D-SPONSOR TECHNICAL SESSION: The Future of Global Engineering Partnerships - Presented by Purdue University
Tue. June 27, 2017 3:30 PM to 5:30 PM
Room A216, Columbus Convention Center

T772A-SPONSOR TECHNICAL SESSION: Bring Robotics into Your Curriculum with BeagleBone Blue - Presented by Texas Instruments
Tue. June 27, 2017 6:15 PM to 7:45 PM
Room A120, Columbus Convention Center

T772C-SPONSOR TECHNICAL SESSION: Efficient Embedded Design Education Kit from ARM University Program - Presented by ARM Ltd, Cambridge UK, and Numato Lab, Electronics City, Bangalore India
Tue. June 27, 2017 6:15 PM to 7:45 PM
Room A121, Columbus Convention Center

WEDNESDAY, JUNE 28TH

W172-SPONSOR TECHNICAL SESSION: Enhance Your Writing Productivity - Identifying Unproductive Habits and Developing Better Ones - Presented by Ohio State
Wed. June 28, 2017 8:00 AM to 9:30 AM
Room A121, Columbus Convention Center

W172A-SPONSOR TECHNICAL SESSION: TI LaunchPad™ for Embedded Systems and IoT Courses - Presented by Texas Instruments
Wed. June 28, 2017 8:00 AM to 9:30 AM
Room A120, Columbus Convention Center

W372-SPONSOR TECHNICAL SESSION: Presented by ARM
Wed. June 28, 2017 11:30 AM to 1:00 PM
Room A121, Columbus Convention Center

W472R-SPONSOR TECHNICAL SESSION: Active Instruction with WileyPLUS - Presented by Wiley
Wed. June 28, 2017 1:30 PM to 3:30 PM
Room A121, Columbus Convention Center